



Material Content Data Sheet



Sales Product Name		TLE42754E		Issued		28. August 2013		
MA#		MA001131782						
Package		PG-SSOP-14-2		Weight*		83.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.311	3.96	3.96	39639	39639
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		412	
	non noble metal	iron	7439-89-6	0.689	0.82		8248	
wire	non noble metal	copper	7440-50-8	27.978	33.49	34.36	334911	343674
	noble metal	gold	7440-57-5	0.131	0.16	0.16	1566	1566
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1151
encapsulation	plastics	epoxy resin	-	4.421	5.29		52925	
	inorganic material	silicondioxide	60676-86-0	43.540	52.13	57.54	521192	575268
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11685	11685
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9189	9189
glue	plastics	epoxy resin	-	0.396	0.47		4745	
	noble metal	silver	7440-22-4	1.189	1.42	1.89	14234	18979
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com